# **Fully Integrated Octal Valve and Pump Controller System on Chip**

The SB0800 device is a valves and pump controller system designed for use in harsh industrial environments.

It has eight high-current low-side drivers for use with solenoid valves, and highside gate drivers for use with controlling two external N-channel MOSFETs, for DC motor and a master relay for solenoid coils. Alongside this, the SB0800 has three analog to digital converters, plus a low-side driver allowing drive resistive charges. The SB0800 boosts an internal charge pump, permitting the high-side drivers to use inexpensive N-channel MOSFETs. The digital I/O pins can be configured for both 5.0 V and 3.3 V levels for easy connection to any microprocessor. The SB0800 uses standard SPI protocol communication.

The SB0800 is a perfect solution for hydraulic and pneumatic applications. This device is powered by SMARTMOS technology.

#### **Features**

- Operating voltage 6.0 V to 36 V
- Eight valves control
	- Four current regulated valves up to 2.25 A (5.0 kHz)
	- Four PWMed valves up to 5.0 A (5.0 kHz)
- High-side predriver for valves protection
- Pump motor predriver up to 500 Hz PWM
- 16-bit SPI interface with watchdog
- Three 10-bit ADC channels
- High-side driver for general purpose ( $R_{DS(on)}$  1.0  $\Omega$ )
- Low-side driver for resistive charge ( $R_{DS(0n)}$  14.0  $\Omega$ )
- Die temperature warning
- Supervision



**SB0800**

#### **Applications**

- Industrial Controller
	- Force
	- Spot Welding
	- **Fluid Coating**
	- Flight Simulator
	- Temperature Control
	- Brake Pressure
	- **Laser Cutting**
	- **Bottle Moulding**
	- Filling Pressure



**Figure 1. SB0800 Simplified 5.0 V Application Diagram**

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# <span id="page-1-1"></span>**1 Orderable Parts**

This section describes the part numbers available to be purchased along with their differences. Valid orderable part numbers are provided on the web. To determine the orderable part numbers for this device, go to<http://www.freescale.com>and perform a part number search for the following device numbers.

#### **Table 1. Orderable Part Variations**



<span id="page-1-0"></span>Notes

1. To order parts in Tape & Reel, add the R2 suffix to the part number.

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# <span id="page-3-0"></span>**2 Internal Block Diagram**



**Figure 2. SB0800 Simplified Internal Block Diagram**

# <span id="page-4-1"></span>**3 Pin Connections**

# <span id="page-4-0"></span>**3.1 Pinout Diagram**



## <span id="page-5-0"></span>**3.2 Pin Definitions**

### **Table 2. SB0800 Pin Definitions**



### **Table 2. SB0800 Pin Definitions (continued)**



<span id="page-6-0"></span>Notes

2. Pins must be shorted together

3. 220 nF/10 V capacitor needed

<span id="page-6-1"></span>4. All GND\_Px pins must be shorted together at the PCB level.

# <span id="page-7-1"></span>**4 General Product Characteristics**

## <span id="page-7-0"></span>**4.1 Maximum Ratings**

### **Table 3. Maximum Ratings**

Voltage parameters are absolute voltages referenced to GND\_A, GND\_D and flag (tied together internally). Exceeding these ratings may cause a malfunction or permanent damage to the device.

![](_page_7_Picture_271.jpeg)

#### **Table 3. Maximum Ratings (continued)**

Voltage parameters are absolute voltages referenced to GND\_A, GND\_D and flag (tied together internally). Exceeding these ratings may cause a malfunction or permanent damage to the device.

<span id="page-8-1"></span>![](_page_8_Picture_265.jpeg)

## <span id="page-8-0"></span>**4.2 Operating Conditions**

This section describes the operating conditions and the current consumptions. Conditions apply to all the following data, unless otherwise noted.

#### **Table 4. Operating Conditions**

Voltage parameters are absolute voltages referenced to GND. Exceeding these ratings may cause a malfunction or permanent damage to the device.

![](_page_8_Picture_266.jpeg)

## <span id="page-9-0"></span>**4.3 Supply Currents**

This section describes the operating conditions and the current consumptions. Conditions apply to all the following data, unless otherwise noted.

#### **Table 5. Supply Currents**

Characteristics noted under conditions 6.0 V  $\leq$  V<sub>PWR</sub>  $\leq$  36 V, 4.75 V  $\leq$  V<sub>CC5</sub>  $\leq$  5.25 V, 3.13 V  $\leq$  V<sub>DOSV</sub>  $\leq$  5.25 V,

-40 °C  $\leq$  T<sub>J</sub>  $\leq$  85 °C, GND = 0 V, unless otherwise noted. Typical values noted reflect the approximate parameter means at T<sub>A</sub> = 25 °C under nominal conditions, unless otherwise noted.

![](_page_9_Picture_238.jpeg)

## <span id="page-9-1"></span>**4.4 Thermal Ratings**

#### **Table 6. Thermal Data**

![](_page_9_Picture_239.jpeg)

<span id="page-9-2"></span>Notes

5. Lead soldering temperature limit is for 10 seconds maximum duration. Lead soldering can be done twice. Device must be delivered in dry pack.

<span id="page-9-3"></span>6. [Freescale's Package Reflow capability meets Pb-free requirements for JEDEC standard J-STD-020C. For Peak Package Reflow Temperature](http://www.freescale.com)  [and Moisture Sensitivity Levels \(MSL\), Go to www.freescale.com, search by part number \[e.g. remove prefixes/suffixes and enter the core ID to](http://www.freescale.com)  view all orderable parts. (i.e. MC33xxxD enter 33xxx), and review parametrics.

## <span id="page-10-0"></span>**4.5 Logical Inputs and Outputs**

### **Table 7. Logical Inputs/Outputs**

V<sub>PWR</sub> = 6.0 to 36 V, VCC5 = 4.75 to 5.25 V, DOSV = 3.13 to 5.25 V, T<sub>J</sub> = -40 to 85 °C, unless otherwise specified.

![](_page_10_Picture_122.jpeg)

# <span id="page-11-0"></span>**5 General Description**

## <span id="page-11-1"></span>**5.1 Block Diagram**

![](_page_11_Figure_2.jpeg)

**Figure 4. SB0800 Functional Block Diagram**

## <span id="page-11-2"></span>**5.2 Functional Description**

The SB0800 device is a valves and pump controller, designed for use in harsh industrial environments, requiring few external components. The SB0800 eight high-current low-side drivers for use with solenoid valves, and high-side gate drivers for controlling two external Nchannel MOSFETs for use with a pump motor and master relay for a solenoid coil. In conjunction with this primary functionality, the SB0800 has one low-side driver to control a resistive load. The SB0800 boosts an internal charge-pump, allowing the high-side drivers to use inexpensive N-channel MOSFETs. The digital I/O pins can be configured for both 5.0 V and 3.3 V levels for easy connection to any microprocessor. Also, the device integrated three Analog to Digital converters. The SB0800 uses standard SPI protocol for communication.

## <span id="page-11-3"></span>**5.3 Features**

This section presents the detailed features of SB0800.

### **Table 8. Device Features Set**

![](_page_11_Picture_158.jpeg)

### **Table 8. Device Features Set (continued)**

![](_page_12_Picture_211.jpeg)

# <span id="page-13-0"></span>**6 Functional Block Description**

# <span id="page-13-1"></span>**6.1 Error Handling**

### **Table 9. Error Handling**

![](_page_13_Picture_344.jpeg)

#### **Table 9. Error Handling (continued)**

![](_page_14_Picture_364.jpeg)

Notes

7. If xxx\_clr\_flt is written "1" by SPI, all SPI flags are set "0", so SW engineer has to read the SPI flag first and then write xxx\_clr\_flt to default value "0".

8. SW engineering can monitor internal supply voltage in real time with ADC reading, and can use fail-safe function. If these ADC results are not in a certain range, uC can reset the SB0800 (see ADC section).

<span id="page-14-0"></span>9. Fail-safe switch off until power is off

## <span id="page-15-0"></span>**6.2 High-side Driver**

### **6.2.1 Function Description**

The high-side driver is intended to control the fail-safe switch for the overall solenoid path, and HD\_G is controlled by the SPI command.

![](_page_15_Figure_3.jpeg)

**Figure 5. High-side Driver**

## **6.2.2 High-side Driver and Fault Protection**

### **6.2.2.1 Overcurrent**

High-side driver protects the external n-channel power FET on HD G in overcurrent conditions. The drain-source voltage of the FET on HD\_G is checked if the high-side driver is switched on. If the measured drain-source voltage exceeds the overcurrent voltage threshold, the output of the overcurrent comparator is enabled. If the output of the comparator is active longer than the defined filter time, the output HD G is switched off. Overcurrent detection logic has a masking time from hd\_on turn-on against malfunctions on transient time. After switching off the power FET on HD G by an overcurrent condition, the power FET can be turned back to a "normal state" by a SPI write 1 to the "HD\_clr\_flt" register, and then turned on by a SPI command.

### **6.2.2.2 Load Leakage Detection**

Each time HD\_G is turned on, the ILCdet current is sourced out of the HD\_S pin for the time  $t_{HD\ LC}$ , to check the external leakage current on the node in the application. The high-side switch on HD\_G is turned on if the measured voltage is over the detection threshold. If this test fails, HD\_G does not turn-on and the fault flag is set to high. The power FET can be turned back to a "normal state" only by a SPI write 1 to the "HD clr flt" register, and then turned on by a SPI command. When the power FET is switched off, the gate capacitance of the FET is discharged by a constant current, which is controlled fast and slow by a SPI command (HPD\_sr).

### **6.2.2.3 External Components of High-side Driver**

For protection, external resistors R<sub>HD\_D</sub>, R<sub>HD\_G</sub>, and R<sub>HD\_S</sub> are required (for example: R<sub>HD\_D</sub> = 100  $\Omega$ , R<sub>HD\_G</sub> = 100  $\Omega$ , R<sub>HD\_S</sub> = 100  $\Omega$ ). The zener clamping is necessary to protect the gate and source. The zener chains are used for avalanche clamping and protection against transients.

### **Table 10. High-side Driver Electrical Characteristics**

V<sub>PWR</sub> = 6.0 to 36 V, VCC5 = 4.75 to 5.25 V, DOSV = 3.13 to 5.25 V, T<sub>J</sub> = -40 to +85 °C, unless otherwise specified.

![](_page_16_Picture_266.jpeg)

## <span id="page-17-0"></span>**6.3 Pump Motor Pre-driver**

### **6.3.1 Function Description**

This module is designed for pump motor predrivers, a maximum of 500 Hz PWM is possible. The pump motor pre-driver can be driven by a SPI command (pd\_on) or through the ADIN1 pin by selecting Adin1 dis bit at "1".

![](_page_17_Figure_3.jpeg)

**Figure 6. Pump Motor Predriver**

### **6.3.2 Fault Detection**

### **6.3.2.1 Overcurrent**

The pump pre-driver protects the external n-channel power FET on PD\_G in overcurrent conditions. The drain-source voltage of the FET on PD\_G is checked if the high-side predriver is switched on. If the measured drain-source voltage exceeds the overcurrent voltage threshold, the output of the overcurrent comparator is enabled. If the output of the comparator is active longer than the defined filter time, the output PD\_G is switched off. Overcurrent detection logic has a masking time from pd\_on turn-on against malfunctions in transient time. The masking time and filter time of the pump predriver is controllable by the SPI bit (See [SPI and Data Register](#page-37-0)). After switching off the power FET on PD G by an overcurrent condition, the power FET can be turned back to a "normal state" by a SPI write 1 to the "PD clr flt" register, and then turned on by a SPI command.

When the power FET is switched off, the gate capacitance of the FET is discharged by a constant current, which is controlled fast and slow by a SPI command (HPD\_sr).

### **6.3.2.2 External Components of Pump Predriver**

Protection of the resistors R<sub>PD\_D</sub>, R<sub>PD\_G</sub>, and R<sub>PD\_S</sub> is required (for example: R<sub>PD\_D</sub> = 2.0 k $\Omega$ , R<sub>PD\_G</sub> = 100  $\Omega$ , R<sub>PD\_S</sub> = 2.0 k $\Omega$ ).

Zener clamping is necessary to protect the gate and source. The zener chains are used for avalanche clamping and protection against transients.

### **Table 11. Pump Motor Predriver Electrical Characteristics**

V<sub>PWR</sub> = 6.0 to 36 V, VCC5 = 4.75 to 5.25 V, DOSV = 3.13 to 5.25 V, T<sub>J</sub> = -40 to +85 °C, unless otherwise specified.

![](_page_18_Picture_256.jpeg)

## <span id="page-19-0"></span>**6.4 Low-side Driver**

### **6.4.1 Functional Description**

The SB0800 is designed to drive inductive loads in low-side configuration. All four channels are monitored by logic and faults are individually reported by the SPI. All external wiring to the loads and supply pins of the device are controlled. The device is self-protected against short-circuit and overtemperature at the outputs.

![](_page_19_Figure_3.jpeg)

**Figure 7. PWM Low-side Driver**

Channel 1 to 4 can work either as current regulator or as PWM. When Channels 1 to 4 work as a current regulator, freewheeling diodes must be connected. Each channel comprises an output transistor, a predriver circuit, a diagnostic circuitry, and a current regulator. The SPI register defines the target output current. The output current is controlled through the output PWM of the power stage. The LSD1-4 current slopes are controlled by a SPI command to reduce switching loss.

The four power outputs consist of DMOS-power transistors with open drain outputs. The output transistor is equipped with an active clamp to limit the voltage at its output during turn-off with inductive loads. When the external fly-back diode is connected, the current re-circulation executes via the diode to the battery. When the diode is not connected, the PWM driver is equivalent to a digital driver. In those conditions, the inductive load forces the output voltage to increase until the voltage at the output is such that the output transistor turns on again. This lasts until the inductor current becomes zero. At that moment, the output transistor turns off. The predriver is in charge of applying the necessary voltage on the output transistor gate to minimize the On-resistance of the output switch.

The duty cycle of PWM low-side drivers is programmed via an 8-bit SPI message. The duty cycle between 0% and 100% can be selected and the LSB of the 8 bits is weighted with an 0.39% duty. Each channel has an 8-bit SPI register of PWM duty cycle.

The PWM low-side driver uses each channel as a digital low-side switch.

PWMx duty cycle = 1111 1111 - Digital low-side switch ON (conducting)

PWMx duty cycle = 0000 0000 - Digital low-side switch OFF

The SB0800 provides interleaved phase shift switching to minimize switching noise of the solenoid coil. Each LSD1 to 4 have this cycle.

![](_page_20_Figure_0.jpeg)

**Figure 8. PWM Valve Control Interleave**

### <span id="page-20-0"></span>**Table 12. Low-side Driver Electrical Characteristics**

V<sub>PWR</sub> = 6.0 to 36 V, DOSV = 3.13 to 5.25 V, T $_{\textrm{J}}$  = -40 to 85 °C, unless otherwise specified.

![](_page_20_Picture_279.jpeg)

#### **Table 12. Low-side Driver Electrical Characteristics (continued)**

![](_page_21_Picture_211.jpeg)

V<sub>PWR</sub> = 6.0 to 36 V, DOSV = 3.13 to 5.25 V, T $_{\textrm{J}}$  = -40 to 85 °C, unless otherwise specified.

Notes

<span id="page-21-0"></span>10. Digital: internal digital signal delivered by interleave synchronization block. See [Figure 8](#page-20-0).

### **6.4.2 LSD1 to LSD4 Current Regulation Driver**

![](_page_21_Figure_6.jpeg)

**Figure 9. PWM Low-side Driver (Current Regulated)**

The load current is sensed by an internal low-side sense FET and digitized by an internal A/D converter. The target value of the current is given SPI messages. A digital current regulation circuitry compares the actual load current with the target current value and steers the duty cycle of the low-side power switch. The PI regulator characteristic can be adjusted via the SPI.

### **6.4.2.1 Target Current**

Each current regulator channel has its own 10-bit target current register. The LSB of the 10 bits is weighted with 2.2 mA. A zero value disables the power stage of the respective channel. A new target current is instantaneously passed to the settling time, which is the settling of the new current value.

PWMx target current value = 00 0000 0000  $\rightarrow$  0 mA PWMx target current value = 00 0000 0001  $\rightarrow$  2.2 mA **…**

PWMx target current value = 11 1111 1110  $\rightarrow$  2.248 A PWMx target current value = 11 1111 1111  $\rightarrow$  2.250 A

![](_page_22_Picture_202.jpeg)

### **6.4.2.2 Current Measurement**

The output current is measured during the "ON' phase of the low-side driver. A fraction of the output current is diverted and (using a "current mirror" circuit) generates across an internal resistance a voltage relative to ground, this being proportional to the output current.

### **6.4.3 PI Characteristics**

Digital PI-regulator with the Transfer function is programmed via the SPI register.

$$
\text{Transfer function:} \quad \frac{KI}{z-1} + KP
$$

The integrator feedback register I charac bits define the regulation behavior of all channels. The default value is 1/8. Both current regulators remain idle until a non-zero value in I charac was programmed. A high proportional feedback value accelerates the regulator feedback and provides a faster settling of the regulated current after disturbances like battery voltage surge.

### **Table 13. Duty Cycle Descriptions**

The duty cycle of PWM output is clamped minimum by options and maximum 100% (see [6.10, "SPI and Data Register"](#page-37-0)).

![](_page_22_Picture_203.jpeg)

#### **Table 13. Duty Cycle Descriptions**

![](_page_23_Picture_367.jpeg)

The duty cycle of PWM output is clamped minimum by options and maximum 100% (see 6.10, "SPI and Data Register").

If the target current value is not reached within the regulation error delay time of  $t_{CRER}$ , the flag of the SPI register "LSDx\_crer" is set to high. The current regulation loop is still running and tries to regulate at the target. Because it is not at the target, the duty cycle is either 100%, or minimum duty cycle by option. LSDx\_crer error detection has no effect on the driver, only SPI fault reporting. The microcontroller can detect the fault through the SPI (LSDx\_crer bit + ADC current reading), and shutdown the driver by sending 0 target current. Set Current – ADC result > "error threshold" during  $t_{CR|ERR}$  then LSDx\_crer is set to 1.

This flag is latched & can be reset by the SPI read (LSDx\_crer).

Each of the four current regulation low-side drivers can be used as a PWM low-side switch.

CR\_disxx flag is enabled HIGH.

The 8 MSB bits of the target current message are the PWM duty cycle.

The first duty is controlled by the SPI bit FDCL (See [SPI and Data Register\)](#page-37-0).

#### **Table 14. LSD1 to LSD4 Current Regulation Driver Electrical Characteristics**

V<sub>PWR</sub> = 6.0 to 36 V, VCC5 = 4.75 to 5.25 V, DOSV = 3.13 to 5.25 V, T<sub>J</sub> = -40 to +85 °C, unless otherwise specified.

![](_page_23_Picture_368.jpeg)

Notes

<span id="page-23-0"></span>11. Maximum regulation deviation performances noted in the table depend on external conditions ( $V_{PWR}$ , load (R,L)).

## <span id="page-24-0"></span>**6.5 Low-side Driver for Resistive load**

### **6.5.1 Power Output Stages**

![](_page_24_Figure_2.jpeg)

**Figure 10. Low-side Driver for Resistive Load Diagram Block**

The low-side driver consists of DMOS-power transistors with open drain output. The low-side driver can be driven by SPI commands or by a MCU through the ADIN2. The low-side driver is composed of an output transistor, a predriver circuit, and diagnostic circuitry. The predriver applies the necessary voltage on the output transistor gate to minimize the On resistance of the output switch. To avoid leakage current path, LD has no sink current.

#### **Table 15. Low-side Driver Electrical Characteristics**

V<sub>PWR</sub> = 6.0 to 36 V, VCC5 = 4.75 to 5.25 V, DOSV = 3.13 to 5.25 V, T<sub>J</sub> = -40 to 85 °C, unless otherwise specified.

![](_page_24_Picture_251.jpeg)

**Timings**  $t_{\text{D ON LD}}$  Turn On Delay Time for LD  $1.0$  s tD\_OFF \_LD Turn Off Delay Time for LD  $1.0$  s

Notes

<span id="page-24-1"></span>12. From Digital Signal to 50% (turn ON) or 50% (turn OFF).  $R_L$  = 1.0 kΩ, V<sub>PWR</sub> = 30V, no capacitor

[\(12\)](#page-24-1)

[\(12\)](#page-24-1)

## **6.5.2 Fault Detection**

### **OpenLoad**

An open condition is detected when the LD output is below the threshold OP<sub>LD</sub> for the defined filter time t<sub>OP\_LD</sub>, the fault bit is set ld\_OP (SPI error flag only). This function only operates during the off state.

#### **VDS State Monitoring**

The  $V_{DS}$  state monitoring gives real time state of LD drain voltage vs OP<sub>LD</sub> voltage. This signal is filtered and sent through the SPI vds\_ld bit. If the V<sub>DS</sub> voltage is higher than OP<sub>LD</sub> with a filter time (T1), vds\_ld is set to "1".

#### **Overcurrent**

When the current is above the overcurrent threshold  $OC<sub>LD</sub>$  for the defined filter time  $t_{OC\ LD}$ , the driver is switched off, a SPI fault bit ld\_OC is set, and the turn-on SPI command is cleared. The driver can be returned to the "normal state" by a SPI write "1" to "LD\_clr\_flt", then turned on by a SPI command (LD\_on).

#### **Overtemperature**

When the temperature is above the overtemperature threshold  $OT_{LD}$  for the defined filter time  $t_{OTLD}$ , the driver is switched off, a SPI fault bit ld\_OT is set, and the turn-on SPI command is cleared. The driver can be returned to the "normal state" when the temperature returns to the normal state, a SPI write "1" to "LD\_clr\_flt", then turning on a SPI command (LD\_on).

#### **Table 16. Low-side Driver Electrical Characteristics**

V<sub>PWR</sub> = 6.0 to 36 V, VCC5 = 4.75 to 5.25 V, DOSV = 3.13 to 5.25 V, T<sub>J</sub> = -40 to 85 °C, unless otherwise specified.

![](_page_25_Picture_257.jpeg)

## <span id="page-26-0"></span>**6.6 Analog to Digital Converter (x3ch)**

ADC is referenced to VCC5 voltage and converts the voltage on 10 bits. It is used to read the following voltages:

- Three analog input pins: ADINx
- Internal voltage supplies (VINT\_A, VINT\_D, V<sub>PRE10</sub>, V<sub>PRE12</sub>, V<sub>CP\_VPWR</sub>)
- Average temperature of die, which is used by the temperature warning detection circuit (TEMP). Refer to the SPI Message Structure, Message #9.
- Allows to read the current drain by the LSD1-4 in PWM mode.

Also, it is possible to use ADIN1 and / or ADIN2 to control respectively the motor pump and / or the low-side driver for resistive load directly by the MCU.

#### **Table 17. Direct Control of Pump and Low-side**

![](_page_26_Picture_315.jpeg)

### **Table 18. ADC Electrical Characteristics**

V<sub>PWR</sub> = 6.0 to 36 V, VCC5 = 4.75 to 5.25 V, DOSV = 3.13 to 5.25 V, T<sub>J</sub> = -40 to 85 °C, unless otherwise specified.

![](_page_26_Picture_316.jpeg)

Notes

TEMP

<span id="page-26-1"></span>13. If ADINx voltage is between VCC5 to max\_rating, the ADC value does not change. Also between VCC5 min and GND, the ADC value does not change.

14. SW engineer can monitor internal supply voltage in real time with ADC, SPI reading, and can use fail-safe function.

## <span id="page-27-0"></span>**6.7 High-side**

### **6.7.1 Function Description**

The device has one high-side, having an integrated high-side switch, controlled by the SPI command HS on. It allows connecting and disconnecting loads like voltage dividers from the supply line, to reach low quiescent current of the total ECU or to driver small size relay driver.

![](_page_27_Figure_3.jpeg)

**Figure 11. High-side Driver**

### <span id="page-27-1"></span>**6.7.2 Fault Detection**

### **6.7.2.1 Ground shift**

With a 2.0 V GND shift on the external relay coil (50  $\Omega$ ), 30 mA could flow through the high-side output (diode between the SB0800\_gnd & the high-side output) without damage to the SB0800 (see [Figure](#page-27-1) 11).

### **6.7.2.2 OpenLoad**

An open condition is detected when the high-side output is higher than the threshold OP\_HS for the defined filter time t<sub>OP\_HS</sub>. The fault bit is set HS op (SPI error flag only). The function only operates during the off state.

### **6.7.2.3** V<sub>DS</sub> State Monitoring

The V<sub>DS</sub> state monitoring gives the real time state of HS drain voltage vs. OP\_HS voltage. This signal is filtered and sent through the SPI vds\_HS bit. If the HS output is lower than OP\_hs with a filter time (T1), vds\_HS is set to "1".

### **6.7.2.4 Overcurrent**

When the current is above the overcurrent threshold OC\_hs for the defined filter time  $t_{OC-HS}$ , the driver is switched off, a SPI fault bit HS oc is set, and the turn-on SPI command is cleared. The driver can be turned back to a "normal state" by a SPI write "1" to "HS clr flt", then a turn on by the SPI command (HS on).

### **6.7.2.5 Overtemperature**

When the temperature is above the overtemperature threshold OT\_hs for the defined filter time  $t_{OT-HS}$ , the driver is switched off, a SPI fault bit HS\_ot is set, and the turn-on SPI command is cleared. The driver can be turned back to a "normal state" when the temperature returns to a normal state, a SPI write "1" to "HS\_clr\_flt", and then a turn on by the SPI command (HS\_on).

### <span id="page-28-0"></span>**Table 19. High-side Electrical Characteristics**

V<sub>PWR</sub> = 6.0 to 36 V, VCC5 = 4.75 to 5.25 V, DOSV = 3.13 to 5.25 V, T<sub>J</sub> = -40 to +85 °C, unless otherwise specified.

![](_page_28_Picture_259.jpeg)

Notes

<span id="page-28-1"></span>15. From digital signal to 50% (turn ON) or 50% (turn OFF).  $R_L$ =1.0 K $\Omega$ , V<sub>PWR</sub> = 30 V, no capacitor

<span id="page-28-2"></span>16. Used OpenLoad detection comparator rise & fall edge filter time

## <span id="page-29-0"></span>**6.8 Monitoring Module**

![](_page_29_Figure_1.jpeg)

**Figure 12. Block Diagram of SB0800 Monitoring Module and MCU**

The monitoring module in SB0800 works independently from the MCU functionality. The SEED is an 8-bit word, initializing the monitoring module and transferred by the SPI. The MCU generates the SEED, and must fetch and send correct calculation results (MR7:0) to the SB0800 monitoring module within a defined time window. The SB0800 monitoring module confirms the result is sent and correct in the time window. ALU checker results of SB0800 monitoring module are transferred to the MCU by the SPI. The monitoring module also calculates the expected correct result, which is compared to the actual result from MCU.

The result from MCU is an 8-bit MR. The 8 bits are sent to the monitoring module via the SPI interface. The monitoring cycle time starts by a write of MR, with the next MR written within in a fixed time window. A new cycle time is started automatically by a write of MR.

![](_page_29_Figure_5.jpeg)

![](_page_29_Figure_6.jpeg)

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ERR\_CNT is a 3-bit counter. An incorrect result leads to incrementing the ERR\_CNT by one, and a correct result leads to decrementing by one. The ERR\_CNT 3-bit can be read by the SPI interface.

### **6.8.0.1 ERR\_CNT Behavior**

Reset with (RSTB pin = "Low")

- IF (ERR\_CNT  $\geq$  101) THEN (RSTB pin = "Low") AND (MON\_CNT reset)
- IF (ERR\_CNT  $\leq$  100) AND (MR = incorrect) THEN (ERR\_CNT = ERR\_CNT+1)
- IF (ERR\_CNT = 000) AND (MR = correct) THEN (ERR\_CNT = ERR\_CNT)
- IF (001  $\leq$  MON CNT  $\leq$  100) AND (MR = correct) THEN (ERR CNT = ERR CNT 1)

The SB0800 monitors the time window of the SPI message #18 without writing to the SEED. The time window  $(t_{WD})$  counter starts with the RSTB pin rising edge. The time window  $(t_{WD})$  counter is reset with the SPI message #18 (with valid parity bit) and restart. If the SPI message #18 (with valid parity bit) is not transferred from the MCU before the time window (t<sub>WD</sub>) end period, the RSTB pin goes to a LOW state for the duration time of  $t_{RSTB-REC}$  and the RST\_wd flag is set "High". When RSTB is at a low state (internal, external), the time window  $(t_{WD})$  counter is reset to zero.

### **6.8.0.2 Linear Feedback Shift Register (LFSR)**

Both the SB0800 monitoring module and the MCU have LFSR for a pseudo-random number generator of ALU checker inputs. LFSR works in parallel with the SB0800 and MCU. LFSR is initialized by the SPI with a SEED 8-bit, then each MR write command generates a new pseudo-random number. The FF hex-value cannot be used for the SEED.

![](_page_30_Figure_10.jpeg)

**Figure 14. Diagram of Linear Feedback Shift Register (LFSR)** 

### **6.8.0.3 ALU Checker**

Both the SB0800 monitoring module and the MCU have an ALU checker. The ALU checker work in parallel with the SB0800 and MCU. The 8-bit input of the ALU checker is the 8-bit output of LFSR. The ALU checker proceeds on five sequential calculations.

Multiplier pseudo-random value by fix value 4 Adder output multiplier by fix value 6 Subtract previous value with fix value 4 Inverting previous value: bitwise complement Divider previous value by fix value 4

![](_page_30_Figure_15.jpeg)

**Figure 15. Diagram of ALU Checker**

### **Table 20. Monitoring Module Electrical Characteristics**

V<sub>PWR</sub> = 6.0 to 36 V, VCC5 = 4.75 to 5.25 V, DOSV = 3.13 to 5.25 V, T<sub>J</sub> = -40 to +85 °C, unless otherwise specified.

![](_page_31_Picture_265.jpeg)

## <span id="page-31-0"></span>**6.9 Supervision**

#### <span id="page-31-1"></span>**Table 21. Reaction to Supply Fault & Reset Condition**

![](_page_31_Picture_266.jpeg)

#### **Table 21. Reaction to Supply Fault & Reset Condition**

![](_page_32_Picture_190.jpeg)

Notes

<span id="page-32-0"></span>17. State defines for the duration of the fault and the following reset recovery time period.

#### **Restart conditions:**

SPI write message #0 has first to be executed to clear any reset or fault flags. Then new SPI command can be sent.

#### **Table 22. Start Point of Reset Recovery Time**

![](_page_32_Picture_191.jpeg)

### **6.9.1 Additional Safety Functions**

### **6.9.1.1 VINT\_A or VINT\_D Undervoltage Supervision**

The SB0800 uses an internal supply for analog functions (VINT\_A) and digital functions (VINT\_D). The supply voltage VINT\_A and VINT\_D are supervised for undervoltage. When the voltage becomes lower than each threshold VINT\_A\_uv and VINT\_D\_uv, the RSTB pin is asserted low after detection filter time  $(t_{V|NT})$ . This reset state will continue until the voltage at pin VINT raises again. And if VINT becomes higher than each threshold VINT\_A\_uv and VINT\_D\_uv for same filter time (t<sub>VINT</sub>), the RSTB Pin goes high after reset recovery time ( $t_{RST<sub>REC</sub>}$  and the related flag of the SPI register is set to high. For stabilization the internal supply VINT\_A & VINT\_D requires external capacitors. Two band-gaps are included in the SB0800, one is for the voltage reference and the other is for the diagnostic. The VINT\_A and VINT\_D voltages are sending through the SPI.

### **6.9.1.2 VCC5 Supervision**

See [Table](#page-31-1) 21 Reset condition and reaction.

### **6.9.1.3 DOSV Supervision**

The supply voltage DOSV is supervised for undervoltage. When the voltage at pin DOSV becomes lower than DOSV\_uv, the RST pin is asserted low after detection filter time  $(t_{VDL}V)$ . This reset state will continue until the voltage at pin DOSV raises again. And if DOSV becomes higher than (DOSV\_uv) for same filter time ( $t_{VDUV}$ ), the RSTB Pin goes high after reset recovery time  $(t_{RST<sub>REC</sub>)$  and the related flag of the SPI register is set to high.

The P53\_CFG pin decides the DOSV pin undervoltage threshold.

![](_page_33_Picture_170.jpeg)

![](_page_33_Figure_9.jpeg)

**Figure 16. Configuration of VCC5 and DOSV for 5.0 V or 3.3 V Application**

### **6.9.1.4 Charge Pump**

The charge pump generates a voltage of typically 12 V above the supply  $V_{PWR}$ . The charge pump voltage is intended for internal use only. No additional load shall be connected to the CP pin. The charge pump requires a capacitor for energy storage and to cover transients. The voltage difference between CP and VPWR can be read by the SPI.

### **6.9.1.5 Internal Clock Supervision (Mismatch MAIN-AUX CLK)**

The SB0800 has two independent clock modules, one is the main supply clock to all SB0800 systems. The other monitors the main clock fault and if a fault is detected, the SB0800 resets with the RST CLK function [\(Table](#page-31-1) 21). This function starts when RSTB is in a high state.

Mutual Supervision of Both Main and Auxiliary Clock:

Clock monitoring continues to perform comparisons between the two clocks sources, CLK1 and CLK2. When everything is working correctly, both clocks are present and both have the same frequency of 14 MHz. If one of the clocks stops or if clocks are misaligned in frequency more than ±25% of 14 MHz ([Table](#page-35-0) 23), an RSTB reset is generated [\(Table](#page-31-1) 21) and a SPI flag is reported (RST\_CLK). The reset flag RST\_CLK (same as other reset flags) is cleared in "clear on read" fashion, or in other words, the flag is cleared by a SPI Read command that reads the flag. In the case of a clock monitoring fault, the clock monitoring process will restart only after the clock monitoring flag (RST\_CLK) is cleared on the first SPI message.

If either CLK1or CLK2 disappears indefinitely, the clock monitoring fault will show anywhere from T1 to 2\*T2. If clock frequencies are misaligned in more than  $\pm 25\%$  of 14 MHz, the clock monitoring fault will show after a time delay of T2, as measured by the reference clock CLK1. The misaligned frequency detection error is measured in time window of T2 and the measurement is based on CLK1 clock as reference, therefore if the CLK1 frequency changes, the time window T2 cannot be guaranteed.

The SB0800 internal clock monitoring function can be disabled by the SPI command (StopCLK2), with no effect of functionality except the clock monitoring function, because CLK1 is activated, but CLK2 is deactivated. Frequency modulation can be controlled by the FM\_amp and FM\_EM bits (See [SPI and Data Register\)](#page-37-0). The SPI command (FM\_EN) enables the frequency modulated oscillator by two deviation frequency to spread the oscillator's energy over a wide frequency band. There are two kinds of deviation frequencies (350 kHz and 700 kHz), which are decided by the SPI command (FM\_amp). This spreading decreases the peak electromagnetic radiation level and improves electromagnetic compatibility (EMC) performance.

If preferred, the sequence following by SPI command (StopCLK2), and later on if decided to reactivate the CLK2 (clock monitoring reactivated), a reset clk can be generated due to the fact the clk2 re-start, and can have a settling time > 2\*T2, 1.0 ms max. In this case, reset is detected during reset recovery time and the CLK\_RST (reading message #0) flag should read in a normal condition.

### **6.9.1.6 Die Temperature Warning**

The SB0800 has 1 temperature warning sensor in the cool place of the die. The threshold of temperature warning is 20 °C below overtemperature. In case of a temperature warning, outputs are not shutdown and the SPI-Bit shows the actual status at accessing time.

### **6.9.1.7 Ground Supervision**

GND-loss monitors the voltage between PGND (global reference GND) and GND\_D. In case of a disconnection of GND\_D vs. all other grounds (pin 2, 4, 13, 37, 46, 51, and back side ground are soldered to ground), a detection GND\_D disconnect as soon as the GND\_D is higher than the threshold (V GL) vs. others grounds, is reported through the flag FGND via the SPI register and set high after a filter time  $(t_{GL})$ .

- 1. Connection degraded (resistive path)
	- A. GND\_D vs other grounds > V\_GL but by having Vint\_D –GND\_D > min voltage required
	- B. SPI communication still possible, and the flag FGND will be at 1
- 2. Disconnection (open physically) during a sequence (in Normal mode), the logic embedded will be frozen, because the voltage Vint  $D$  –GND  $D$  < min voltage required
	- A. No SPI communication is possible
	- B. If GND D is reconnected normally, SPI communication recovers and the flag FGND will be at 1

### <span id="page-35-0"></span>**Table 23. Electrical Characteristics**

V<sub>PWR</sub> = 6.0 to 36 V, VCC5 = 4.75 to 5.25 V, DOSV = 3.13 to 5.25 V, T<sub>J</sub> = -40 to +85 °C, unless otherwise specified.

![](_page_35_Picture_263.jpeg)

### **Table 23. Electrical Characteristics (continued)**

![](_page_36_Picture_212.jpeg)

![](_page_36_Picture_213.jpeg)

#### **Table 23. Electrical Characteristics (continued)**

V<sub>PWR</sub> = 6.0 to 36 V, VCC5 = 4.75 to 5.25 V, DOSV = 3.13 to 5.25 V, T<sub>J</sub> = -40 to +85 °C, unless otherwise specified.

![](_page_37_Picture_190.jpeg)

Notes

<span id="page-37-2"></span>18. The t<sub>CLK</sub> parameter is decided by a frequency checker and comparing two clocks. If either main clock or AUX clock frequency disappears longer than T1, the SB0800 goes to reset by the clock frequency checker and the CLK\_RST flag will be detected. Meanwhile, comparing the main clock and AUX clock is done during T2 and the SB0800 is possible to go to reset every T2. Because measurement and reset activation are asynchronous,  $t_{CLK}$  can reach  $2*T2$  in the worst case by comparing two clocks.

<span id="page-37-1"></span>19. For more details, refer to the HD\_G & PD\_G parameters

Write 1 to any xxx clr flt register will create a reset of the fault flag during 1 clock period after the SPI message. xxx clr flt automatically goes to "0" after 1 clock from fault flag reset.

![](_page_37_Figure_7.jpeg)

**Figure 17. Timing Diagram of xxx\_clr\_flt**

## <span id="page-37-0"></span>**6.10 SPI and Data Register**

### **6.10.1 Function Description**

The SPI serial interface has the following features:

- Full duplex, four-wire synchronous communication
- Slave mode operation only
- Fixed SCLK polarity and phase requirements
- Fixed 16-bit command word
- SCLK operation up to 10.0 MHz

The Serial Peripheral Interface (SPI) is used to transmit and receive data synchronously with the MCU. Communication occurs over a fullduplex, four-wire SPI bus. The 34SB0800 device operates only as a slave device to the master, and requires four external pins; SI, SO, SCLK, and CSB. All words are 16 bits long and MSB is sent first.

The SPI simultaneously turns on the serial output SO and returns the MISO return bits. When receiving, valid data is latched on the rising edge of each SCLK pulse. The serial output data is available on the rising edge of SCLK, and transitions on the falling edge of SCLK. The number of clock cycles occurring on the pin SCLK while the CSB pin is asserted low must be 16. If the number of clock pulses is not 16 or a parity fault, the SPI MOSI data is ignored. The SB0800 takes even parity. On next data read SO message, "Fmsg" bit sets to 1, and other data bits sets to 0. The parity bit sets to 1. On the first SPI communication after reset, the read SO message sets to 1010101010101010.

The fault registers are double buffered. The first buffer layer latches a fault at the time the fault is detected. This inner layer buffer clears when the fault condition is no longer present and the fault bit communicates to the MCU by a MISO response. The second layer buffer latches the output of the inner layer buffer whenever the CSB pin transitions from low to high. The output of the second layer buffer is transferred to the shift register after the corresponding MOSI command is received from the MCU.

![](_page_38_Figure_1.jpeg)

**Figure 18. SPI Timing Diagram**

### **Table 24. SPI Timing Electrical Characteristics**

VPWR = 6.0 to 36 V, VCC5 = 4.75 to 5.25 V, DOSV = 3.13 to 5.25 V, T<sub>J</sub> = -40 to 85 °C, unless otherwise specified.

![](_page_38_Picture_238.jpeg)

Notes

<span id="page-38-0"></span>20. The inputs of the SPI module (SCLK, CSB, SI) are driven between 0 V and DOSV voltage.

## **6.10.2 SPI Message Structure**

![](_page_39_Picture_779.jpeg)

Notes

21. MSB(B15) of both write and read messages is parity bit, whereas only B14 of read message is Fmsg, which show previous write message fault.

22. The 'X' bit is used for tests manufacturing.

## **6.10.3 SPI Message Description**

## **6.10.3.1 Message #0**

### **Table 25. Write message**

![](_page_40_Picture_286.jpeg)

![](_page_40_Picture_287.jpeg)

### **Table 26. Read message**

![](_page_40_Picture_288.jpeg)

![](_page_40_Picture_289.jpeg)

![](_page_41_Picture_154.jpeg)

## **6.10.3.2 Message #1**

### <span id="page-41-0"></span>**Table 27. Write message**

![](_page_41_Picture_155.jpeg)

![](_page_41_Picture_156.jpeg)

![](_page_42_Picture_140.jpeg)

### **Table 28. Read message**

![](_page_42_Picture_141.jpeg)

![](_page_42_Picture_142.jpeg)

## **6.10.3.3 Message #2**

Reserved

### **6.10.3.4 Message #3**

### **Table 29. Write message**

![](_page_43_Picture_244.jpeg)

![](_page_43_Picture_245.jpeg)

### **Table 30. Read message**

![](_page_43_Picture_246.jpeg)

![](_page_43_Picture_247.jpeg)

![](_page_44_Picture_127.jpeg)

### **6.10.3.5 Message #4**

### **Table 31. Write message**

![](_page_44_Picture_128.jpeg)

![](_page_44_Picture_129.jpeg)

### **Table 32. Read message**

![](_page_44_Picture_130.jpeg)

![](_page_44_Picture_131.jpeg)

### **6.10.3.6 Message #5**

### **Table 33. Write message**

![](_page_45_Picture_174.jpeg)

![](_page_45_Picture_175.jpeg)

### **Table 34. Read message**

![](_page_45_Picture_176.jpeg)

![](_page_45_Picture_177.jpeg)

### **6.10.3.7 Message #6**

### **Table 35. Write message**

![](_page_46_Picture_234.jpeg)

![](_page_46_Picture_235.jpeg)

### **Table 36. Read message**

![](_page_46_Picture_236.jpeg)

![](_page_46_Picture_237.jpeg)

### **6.10.3.8 Message #7**

### **Table 37. Write message**

![](_page_47_Picture_226.jpeg)

![](_page_47_Picture_227.jpeg)

#### **Table 38. Read message**

![](_page_48_Picture_202.jpeg)

![](_page_48_Picture_203.jpeg)

### **6.10.3.9 Message #8**

### **Table 39. Write message**

![](_page_48_Picture_204.jpeg)

![](_page_48_Picture_205.jpeg)

### **Table 40. Read message**

![](_page_48_Picture_206.jpeg)

![](_page_49_Picture_76.jpeg)

### **6.10.3.10 Message #9**

### **Table 41. Write message**

![](_page_50_Picture_176.jpeg)

![](_page_50_Picture_177.jpeg)

#### **Table 42. Read message**

![](_page_50_Picture_178.jpeg)

![](_page_50_Picture_179.jpeg)

### **6.10.3.11 Message #10**

### **Table 43. Write message**

![](_page_51_Picture_209.jpeg)

![](_page_51_Picture_210.jpeg)

### **Table 44. Read message**

![](_page_51_Picture_211.jpeg)

![](_page_51_Picture_212.jpeg)

![](_page_52_Picture_273.jpeg)

## **6.10.3.12 Message #11**

### **Table 45. Write message**

![](_page_52_Picture_274.jpeg)

![](_page_52_Picture_275.jpeg)

### **Table 46. Read message**

![](_page_52_Picture_276.jpeg)

![](_page_52_Picture_277.jpeg)

![](_page_53_Picture_236.jpeg)

## **6.10.3.13 Message #12**

#### **Table 47. Write message**

![](_page_53_Picture_237.jpeg)

![](_page_53_Picture_238.jpeg)

#### **Table 48. Read message**

![](_page_53_Picture_239.jpeg)

![](_page_54_Picture_237.jpeg)

## **6.10.3.14 Message #13**

### **Table 49. Write message**

![](_page_54_Picture_238.jpeg)

![](_page_54_Picture_239.jpeg)

### **Read message**

![](_page_55_Picture_217.jpeg)

![](_page_55_Picture_218.jpeg)

### **6.10.3.15 Message #14**

### **Table 50. Write message**

![](_page_55_Picture_219.jpeg)

![](_page_55_Picture_220.jpeg)

### **Read message**

![](_page_56_Picture_198.jpeg)

![](_page_56_Picture_199.jpeg)

### **6.10.3.16 Message #15**

### **Table 51. Write message**

![](_page_56_Picture_200.jpeg)

![](_page_56_Picture_201.jpeg)

### **Read message**

![](_page_56_Picture_202.jpeg)

![](_page_57_Picture_172.jpeg)

## **6.10.3.17 Message #16**

### **Table 52. Write message**

![](_page_57_Picture_173.jpeg)

![](_page_57_Picture_174.jpeg)

### **Read message**

![](_page_57_Picture_175.jpeg)

![](_page_58_Picture_164.jpeg)

## **6.10.3.18 Message #17**

### **Table 53. Write message**

![](_page_58_Picture_165.jpeg)

![](_page_58_Picture_166.jpeg)

### **Read message**

![](_page_58_Picture_167.jpeg)

![](_page_59_Picture_196.jpeg)

## **6.10.3.19 Message #18**

### **Table 54. Write message**

![](_page_59_Picture_197.jpeg)

![](_page_59_Picture_198.jpeg)

#### **Table 55. Read message**

![](_page_59_Picture_199.jpeg)

![](_page_59_Picture_200.jpeg)

### **6.10.3.20 Message #19 to 23**

Reserved

### **6.10.3.21 Message #24**

#### **Table 56. Write message**

![](_page_60_Picture_189.jpeg)

![](_page_60_Picture_190.jpeg)

#### **Table 57. Read message**

![](_page_60_Picture_191.jpeg)

![](_page_60_Picture_192.jpeg)

### **6.10.3.22 Message #25**

#### **Table 58. Write message**

![](_page_60_Picture_193.jpeg)

![](_page_61_Picture_196.jpeg)

#### **Table 59. Read message**

![](_page_61_Picture_197.jpeg)

![](_page_61_Picture_198.jpeg)

### **6.10.3.23 Message #26**

### **Table 60. Write message**

![](_page_61_Picture_199.jpeg)

![](_page_61_Picture_200.jpeg)

### **Table 61. Read message**

![](_page_61_Picture_201.jpeg)

![](_page_61_Picture_202.jpeg)

# <span id="page-62-0"></span>**7 Typical Applications**

## <span id="page-62-1"></span>**7.1 Application Diagrams**

This section presents a typical Industrial applications schematic using SB0800, as shown in **Figure 19.** 

![](_page_62_Figure_3.jpeg)

<span id="page-62-2"></span>**Figure 19. Industrial Valves and Pump Control Unit Simplified Diagram**

# <span id="page-63-0"></span>**8 Packaging**

## <span id="page-63-1"></span>**8.1 Package Mechanical Dimensions**

Package dimensions are provided in package drawings. To find the most current package outline drawing, go to [www.freescale.com](http://www.freescale.com) and perform a keyword search for the drawing's document number.

![](_page_63_Picture_50.jpeg)

![](_page_64_Figure_0.jpeg)

![](_page_64_Picture_71.jpeg)

![](_page_65_Figure_0.jpeg)

![](_page_65_Picture_35.jpeg)

![](_page_66_Figure_0.jpeg)

![](_page_66_Picture_41.jpeg)

NOTES:

- 1. DIMENSIONS ARE IN MILLIMETERS.
- 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
- $\sqrt{3}$ . DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- $\sqrt{4}$  dimensions to be determined at seating plane c.
- $\circ$  DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM DIMENSION BY MORE THAN 0.08 MM. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION 0.07 MM.
- A DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 MM<br>PER SIDE, DIMENSIONS ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
- $\sqrt{2}$  EXACT SHAPE OF EACH CORNER IS OPTIONAL.
- $\sqrt{8}$  THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.10 MM AND 0.25 MM FROM THE LEAD TIP.
- $\sqrt{9}$  HATCHED AREA TO BE KEEP OUT ZONE FOR PCB ROUTING.

![](_page_67_Picture_57.jpeg)

# <span id="page-68-0"></span>**9 Revision History**

![](_page_68_Picture_40.jpeg)

![](_page_69_Picture_0.jpeg)

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![](_page_69_Picture_9.jpeg)